Claims

1. A continuous method of forming a busbar, the method comprising continuously providing an electrically conductive material having a first major surface with longitudinal edges, supplying an adhesive material protected with a siliconized paper release liner and continuously bringing ~~an~~ the adhesive material into contact with the electrically conductive material and securing the adhesive material to the first major surface of the electrically conductive material such that the adhesive material is inboard of both of the longitudinal edges of the first major surface of the electrically conductive material and located about a centre line of the first major surface and is able subsequently to secure the first major surface of the busbar at a site of use.

~~2. A method according to Claim 1, comprising forming the busbar at a rate in excess of 400mm/s, preferably at a rate in excess of 410, 420, 430, 440, 450, 460, 470, 480, 490 or 500 mm/s.~~

~~3. A method according to Claim 1 or 2, comprising securing the adhesive material to the electrically conductive material inboard of the longitudinal edges of the first major surface of the electrically conductive material, so as to provide a border extending at least 0.5mm inboard of the or each longitudinal edge.~~

~~4. A method according to any preceding Claim, comprising securing a cover layer to a second major surface of the electrically conductive material.~~

~~5. A method according to Claim 4, comprising securing the cover layer such that it overhangs each longitudinal edge of the second major surface.~~

~~6. A busbar (1, 31) for installation on or in a structure, the busbar (1, 31) comprising a length of electrically conductive material (2, 32) having a, preferably dimensionally invariant, adhesive material (3, 33) secured along a first major surface (2a, 32a) along the length thereof and is able to secure the first major surface of the electrically conductive material of the busbar (1, 31) at a site of use, characterised in that the adhesive material (3, 33) is inboard of both of the longitudinal edges of the first major surface of the electrically conductive material (2, 32).~~

7. A busbar (1, 31) according to Claim 6, wherein the electrically conductive material (2, 32) comprises an electrically conductive substrate (21, 321) provided with a protective coating (22, 322).

8. A busbar (1, 31) according to any of Claims 6 or 7, wherein the adhesive material (3, 33) comprises a carrier substrate with a pair of major surfaces, each of which carry adhesive.

9. A busbar (1, 31) according to any of Claims 6, 7 or 8, wherein the adhesive material (3, 33) is electrically conductive or non-electrically conductive.

10. A busbar (1, 31) according to Claim 9, wherein the adhesive material (3, 33) is electrically conductive and wherein the electrically conductive adhesive material (3, 33) is conductive in one or two planes but not a third, or in one plane but not the other two.

11. A busbar (1, 31) according to any of Claims 6 to 10, wherein the adhesive material (3, 33) covers more than 25% of the surface area of one side of the electrically conductive material (2, 32), for example more than, 30, 35, 40, 45, 50, 55, 60, 65, 70, 75, 80, 85, 90, 95% of the surface area of the conductive material (2, 32).

12. A busbar (1, 31) according to any of Claims 6 to 11, wherein the adhesive material (3, 33) is less than 150 μm thick, for example less than 100, 95, 90, 85, 80, 75, 70, 65, 60 or 55 μm thick.

13. A busbar (1, 31) according to any of the Claims 6 to 12, comprising a cover layer (34) on the obverse face to that of the adhesive layer (3, 33) and preferably is less than 50 x 10^{-6}m thick.

14. An apparatus (100) for continuously forming a busbar (1, 31), the apparatus comprising means (102) to supply a length of conductive material (2, 32), means (103) to supply an adhesive material (3, 33), means (104a, 104b, 111, 112, 113, 114, 115, 116) to bring adhesive material (3, 33) into contact with a first major surface (2a, 32a) of the length of conductive material (2, 32), means (104a, 104b) to heat and or press the adhesive material (3, 33) at the point of contact to the conductive material (2, 32) thereby to secure the adhesive material (3, 33) along the length of the conductive material (2, 32) and inboard of both of the longitudinal edges of the first major surface

~~of the conductive material (2, 32) to thereby form a busbar (1, 31), where the adhesive material (3, 33) is able subsequently to secure the first major surface of the busbar (1, 31) at a site of use.~~